



PATENT APPLICATION
Do. No. 4591-224

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Ki-Nam KIM and Yoon-Jong SONG

Serial No. 10/066,172 Examiner: Tran, Long K

Confirmation No. 2722

Filed: January 30, 2002 Group Art Unit: 2818

For: FERROELECTRIC MEMORY DEVICE AND METHOD OF FORMING THE SAME

BOX NON FEE AMENDMENT
Assistant Commissioner for Patents,
Washington, D.C. 20231

Responsive to the Office Action dated October 16, 2002, enclosed is an amendment in the above-identified application.

The fee has been calculated as shown below.

TECHNOLOGY CENTER 2800

RECEIVED

<u>CLAIMS AS AMENDED</u>					
For:	Number After Amendment	Previous Number	Extra	Rate	Additional Fee
Total Claims	4	24	0	x \$18 =	\$0
Independent Claims	1	4	0	x \$84 =	\$0
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0

*greater of twenty (20) or number for which fee has been paid

**greater of three (3) or number for which fee has been paid

Respectfully submitted,

MARGER JOHNSON & McCOLLOM, P.C.



20575

PATENT TRADEMARK OFFICE



Alan T. McCollom
Reg. No. 28,881

MARGER JOHNSON & McCOLLOM, P.C.
1030 SW Morrison Street
Portland, OR 97205
(503) 222-3613



PATENT APPLICATION
Do. No. 4591-224

RECEIVED
JAN 27 2003

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Ki-Nam KIM and Yoon-Jong SONG

Serial No. 10/066,172 Examiner: Tran, Long K

Confirmation No. 2722

Filed: January 30, 2002 Group Art Unit: 2818

For: FERROELECTRIC MEMORY DEVICE AND METHOD OF FORMING
THE SAME

BOX NON FEE AMENDMENT
Assistant Commissioner for Patents
Washington, D.C. 20231

#31 Small HA
Approved
1/30/03

RESPONSE TO OFFICE ACTION

Responsive to the Office Action dated October 16, 2002, please amend the application as follows.

IN THE CLAIMS

For the Examiner's convenience, any and all amendments to the pending claims are incorporated and presented below in clean form.

21. (Amended) A ferroelectric memory device comprising:
a first interlayer insulating layer formed on a semiconductor substrate;
a buried contact structure electrically connected to the substrate through a first contact hole extending through the first interlayer insulating layer, the buried contact structure formed on the first interlayer insulating layer;
a blocking layer formed on the buried contact structure and the first interlayer insulating layer;
a second interlayer insulating layer formed on the blocking layer; and
a ferroelectric capacitor that fills a second contact hole and connects to the buried contact structure through the second contact hole that penetrates the second interlayer insulating layer and the blocking layer, the ferroelectric capacitor being formed on the second interlayer insulating layer.